



Material Content Data Sheet



Sales Product Name		BFP 780 H6327		Issued		1. August 2018		
MA#		MA001151148						
Package		PG-SOT343-4-2		Weight*		6.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		259	
	noble metal	gold	7440-57-5	0.007	0.10		1005	
	inorganic material	silicon	7440-21-3	0.061	0.88	1.01	8849	10113
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		99	
	non noble metal	titanium	7440-32-6	0.003	0.05		497	
	non noble metal	chromium	7440-47-3	0.010	0.15		1490	
	non noble metal	copper	7440-50-8	3.433	49.46	49.67	494632	496718
wire	noble metal	gold	7440-57-5	0.010	0.15	0.15	1487	1487
encapsulation	organic material	carbon black	1333-86-4	0.030	0.43		4318	
	plastics	epoxy resin	-	0.644	9.28		92841	
	inorganic material	silicondioxide	60676-86-0	2.323	33.47	43.18	334659	431818
leadfinish	non noble metal	tin	7440-31-5	0.199	2.87	2.87	28705	28705
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31159	31159
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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